

A Compact Real-Time Thermal Imaging System Based on Heterogeneous System-on-Chip

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Thermal Imaging

- Adaptability for wide-broad scenarios
 - Robust for low-light conditions
- Privacy protection
 - Hard to identify human visual characteristics
- Detection of human-invisible objects
 - Hidden objects can be inspected



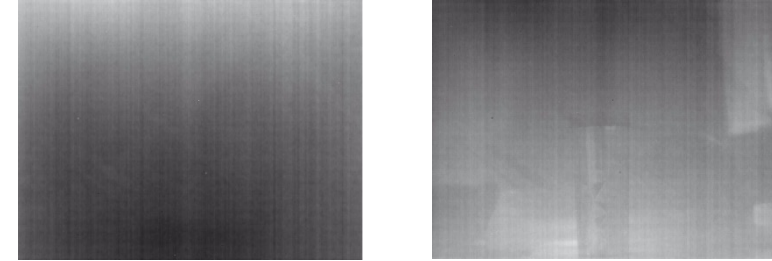
[1] Kowalski, M. Hidden Object Detection and Recognition in Passive Terahertz and Mid-wavelength Infrared. *J Infrared Milli Terahz Waves* 40, 1074–1091 (2019)

General Challenges in Thermal Imaging

- **Fixed-pattern noise**

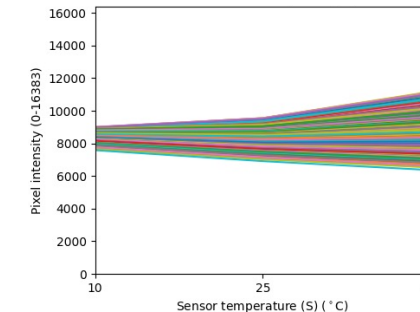
- ROIC noise (IRFPA)
- Low energy level of IR

Non-uniformity
correction (NUC)



- **Thermal drift noise**

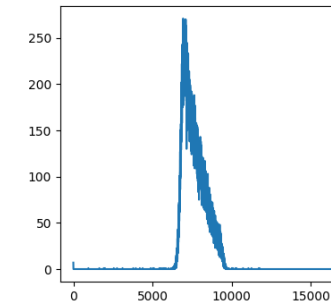
- Thermistors ← affected by internal temp.



- **Dense intensity distribution**

- low quantization levels than detectable temp. range

Contrast enhancement is essential
ex) Min-Max Stretching, HistEq, CLAHE, ...



Previous Solutions & Challenges

- **Two-point correction (TPC)-based NUC**
 - Pixel-wise algorithm based on linear expression
 - Great overall image quality
 - Too much coefficients → Hard to apply for real-time high-resolution, high FPS video
 - Requires run-time calibration to maintain the quality
 - Not considering the internal thermal energy → Prevalent interruption is required
- **Scene-based NUC & Neural Network-based NUC**
 - Use real-time image frame as a reference source
 - Does not require many coefficients → Optimized for high bitrate video.
 - Negative effects exist
 - Image blurring, Ghosting, ...

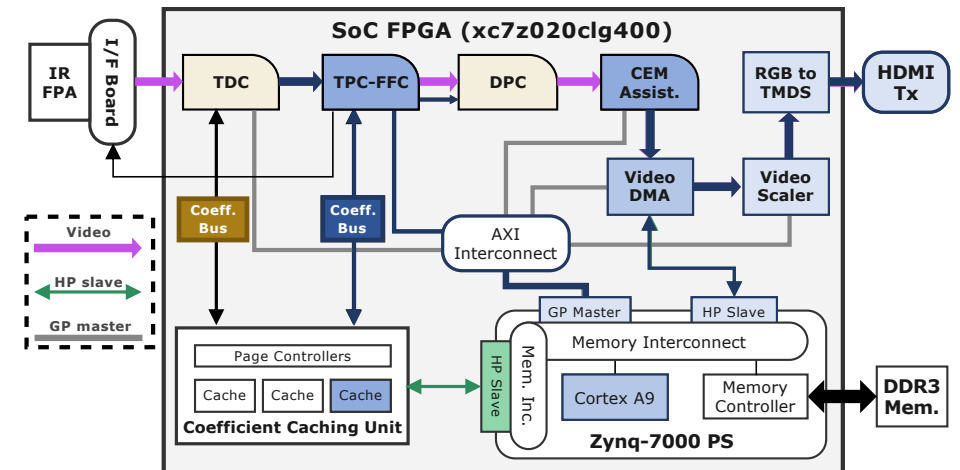
Our Previous Solution: SoC FPGA-Based Image Processor (DSD 2023)

- **Algorithm side**

- Three-layer TPC-based NUC
 - Thermal drift compensation (TDC): Reduce the prevalence of run-time calibration
 - Two-point correction (TPC): Avoid image blurring and ghosting artifacts
 - Defect pixel correction (DPC): Replace defective pixels with appropriate value
- Contrast enhancement
 - Min-max stretching: Reduce compute load

- **System side**

- SoC FPGA-based system design
 - FPGA (PL): Execute NUC
 - DRAM caching for raster-scan-ordered processing
→ Eliminate frame buffer BRAMs
 - PS: Execute contrast enhancement
 - Using pre-calculated min/max derived by the PL side



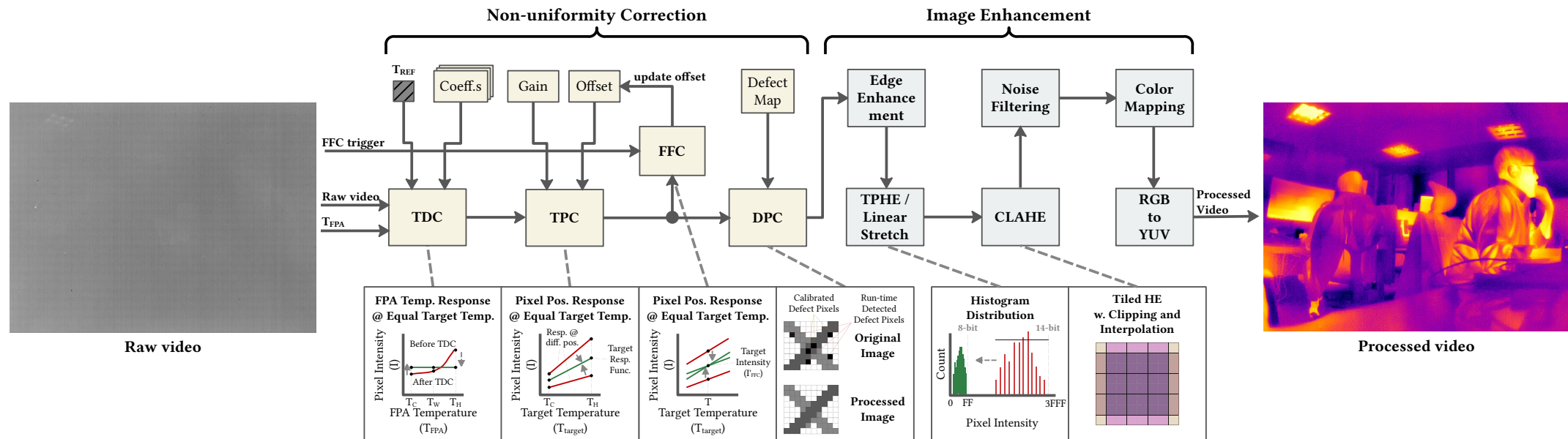
Limitations & Challenges

- **FPGA-based systems** (DSD 2023, Sensors 2024, ...)
 - Higher BOM costs compared to the embedded SoC solutions
- **Contrast enhancement algorithms**
 - Min-max stretching (DSD 2023) / Histogram Equalization (Sensors 2024)
 - Pro: Lower compute loads → Appropriate for lightweight embedded systems
 - Con: No locality enhancements → Limited adaptability
 - Clip-Limited Adaptive Histogram Equalization (CLAHE)
 - Pro: Parameterized locality enhancements → Adaptable to diverse scenarios
 - Con: Current real-time implementation relies on FPGAs → Higher cost

Our Solution

- **Goal:** No FPGAs, Advanced contrast enhancement, Higher throughput
- **Algorithm side**
 - TPC-based Multi-layer NUC algorithm: Similar to our previous solution.
 - Two-layer contrast enhancement
 - Histogram Equalization + CLAHE
- **System Side**
 - Lightweight Heterogeneous SoC
 - Compactness (Even smaller than tiny SoC FPGAs, One LPDDR2 Memory Chip)
 - Optimized Workload Distribution: DSPs, IPUs, Embedded Vision Engine (EVE).
 - SW Optimizations: DSP (SIMD, VLIW), Cache, Hardware IP (ISP).

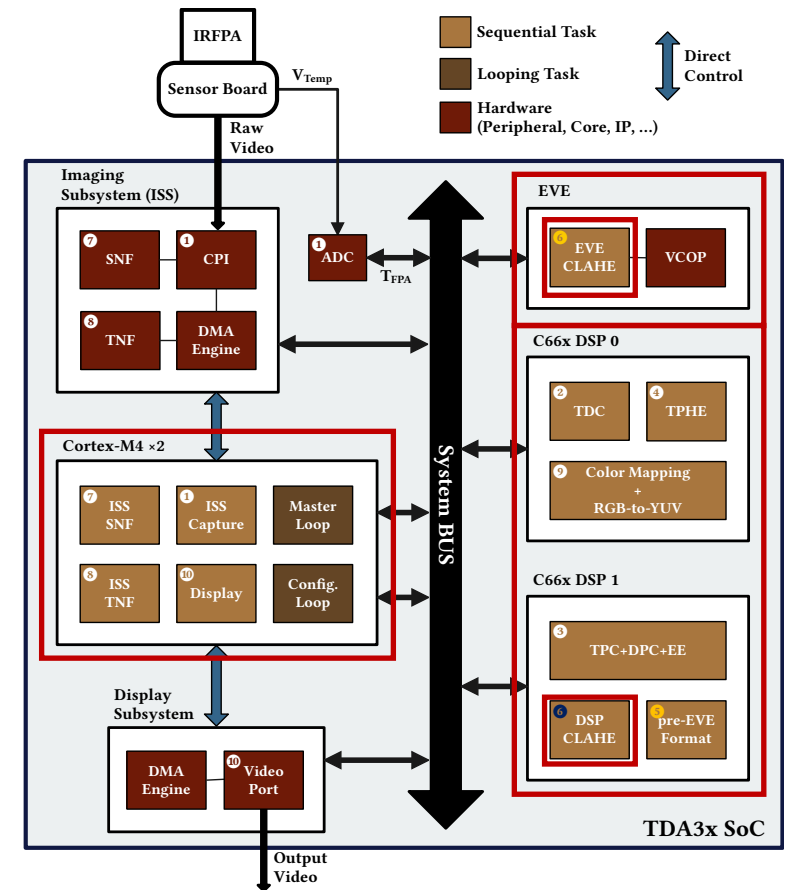
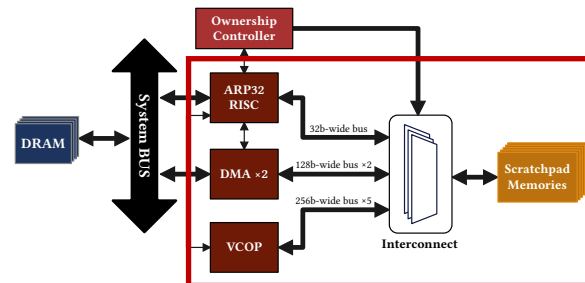
Image Processing Architecture



- **NUC stack: TDC + TPC + DPC**
- **Image enhancement stack**
 - Edge Enhancement
 - Two-layer contrast enhancement: TPHE, CLAHE
 - Color mapping & Formatting (RGB to YUV)

Workload Distribution

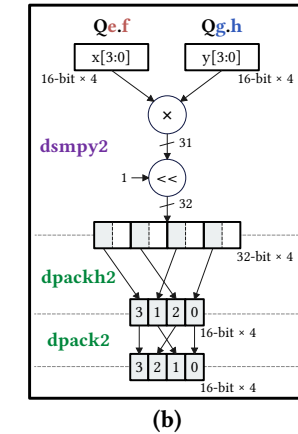
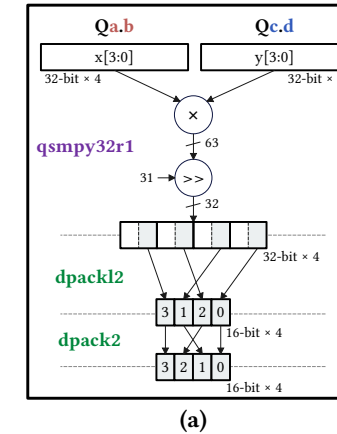
- **2x C66x DSPs**
 - Suitable for intensive processing with run-time configuration
 - Most image processing tasks
- **2x IPU (Cortex-M4)**
 - Not appropriate for intensive operations → managing tasks
- **EVE**
 - Particularly optimized to execute CLAHE.
 - Run-time configuration is limited
 - Isolated data-path requiring system stall
 - Distinctive SW design flow
 - We provide the options to execute CLAHE on the DSP or EVE.



SW Optimization (i) – SIMD / VLIW

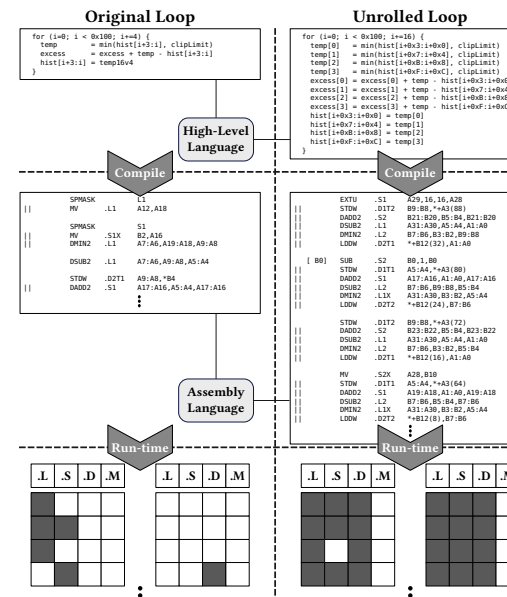
• SIMD Kernels

- 4-way fixed-point multiplication
- Adaptable to diverse configurations
- (a): 32 by 32-bit multiply and convert to 16-bit
 - Condition: $a + b = 31$, $c + d = 31$, $b + d = 31$
- (b): 16 by 16-bit multiply and convert to 16-bit
 - Condition: $e + f = 15$, $g + h = 15$, $f + h = 15$

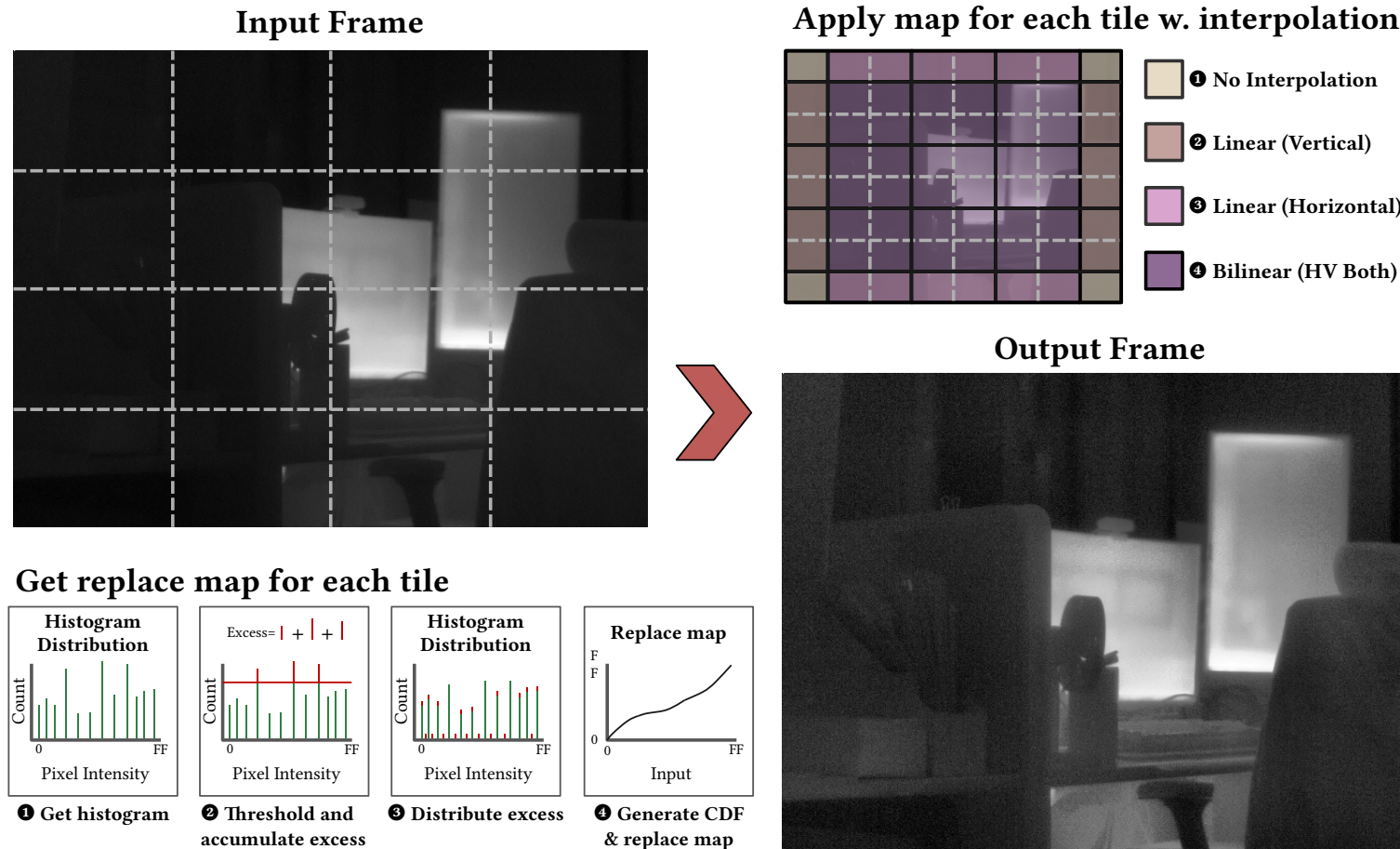


• VLIW Optimization

- Manual unlooping
 - Increase instruction-level parallelism

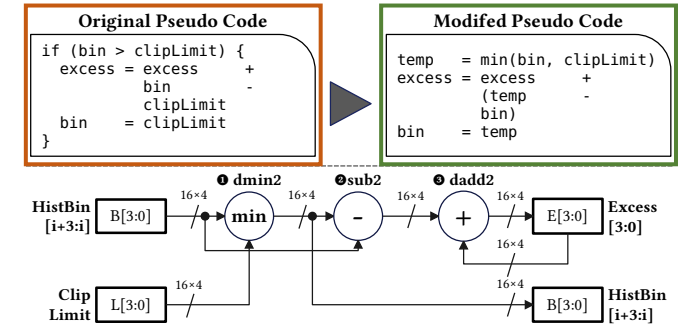
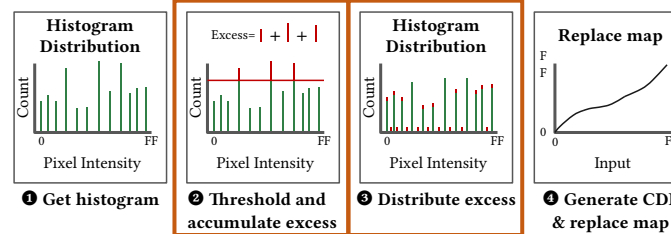


SW Optimization (ii) - CLAHE



SW Optimization (ii) - CLAHE

- **Thresholding Kernels**
 - 4-way SIMD operation
 - Replaces conditional branch



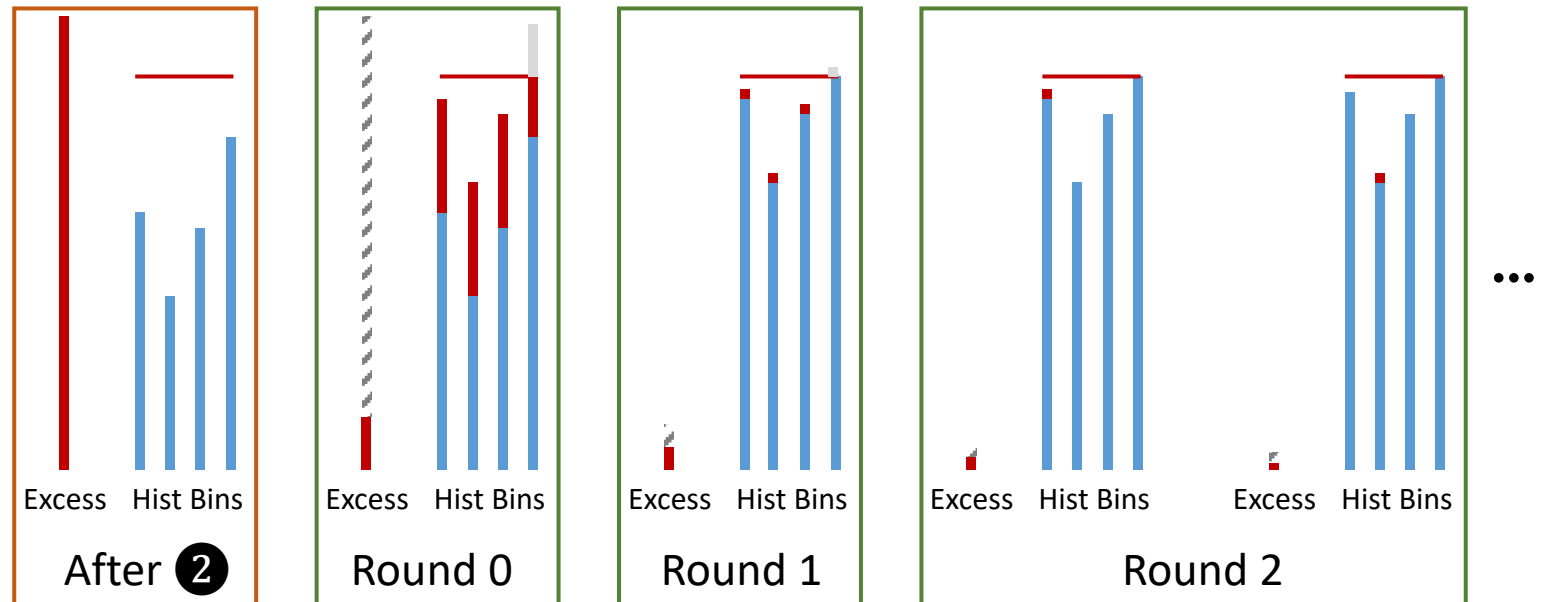
- **Excess Distribution**
 - Three round operation

```

#### Round One: Fast Distribution
while (excessTotal > 0xFF) {
    dist16v4 = duplicate_by_four(excessTotal >> 8)
    pass16v4 = {0,0,0,0}
    for (i=0; i < 0x100; i+=4) {
        temp16v4 = min(hist[i+3:i] + dist16v4, clipLimit16v4)
        pass16v4 = pass16v4 + temp16v4 - hist[i+3:i]
        hist[i+3:i] = temp16v4
    }
    excessTotal = excessTotal - sum(pass16v4)
}

#### Round Two: Distribute by Up to Four
for (j=0; excessTotal > 4; j+=4) { // j is unsigned 8-bit
    temp16v4 = min(hist[j+3:j] + {1,1,1,1}, clipLimit16v4)
    excessTotal = excessTotal - sum(temp16v4 - hist[j+3:j])
    hist[j+3:j] = temp16v4
}

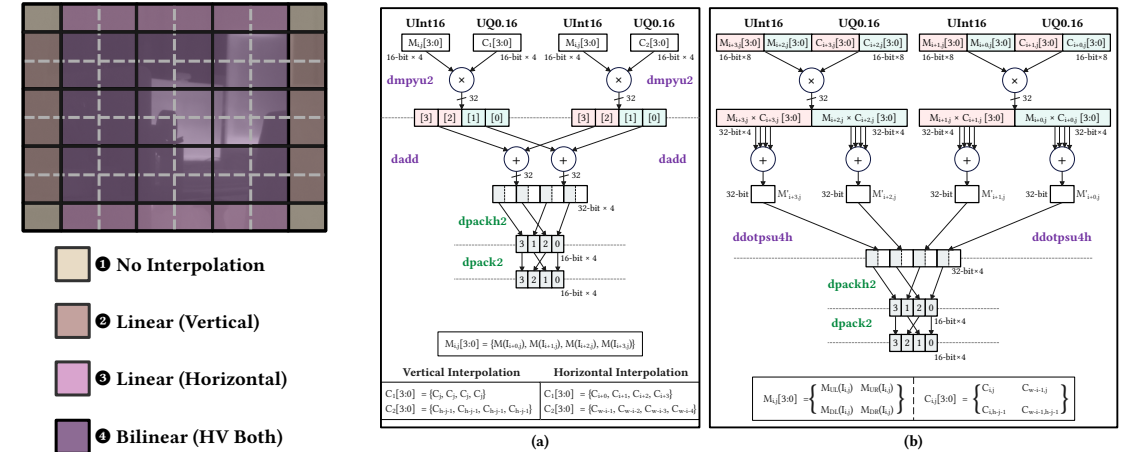
#### Round Three: Distribute Each by One
for (; excessTotal > 0; j+=1) {
    temp = min(hist[j] + 1, clipLimit)
    excessTotal = excessTotal - temp + hist[j]
}
    
```



SW Optimization (ii) - CLAHE

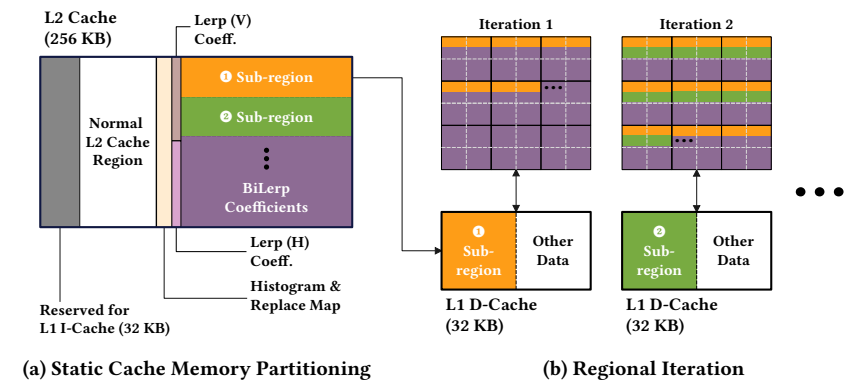
• Interpolation SIMD Kernels

- Convert division to fixed-point multiplication
- Use coefficients from the memory
 - Calculated at
 - System boot time
 - Run-time configuration



• Cache Optimization

- Static Cache Memory Partitioning
 - Ensure no L2 misses on coefficient access
- Regional Iteration
 - Split each tile by sub-regions (adjustable)
 - Iteratively access to
 - Increase L1 cache hit rate



Evaluation – Visualized

- **NUC**

- **Two-Point Correction (TPC)**

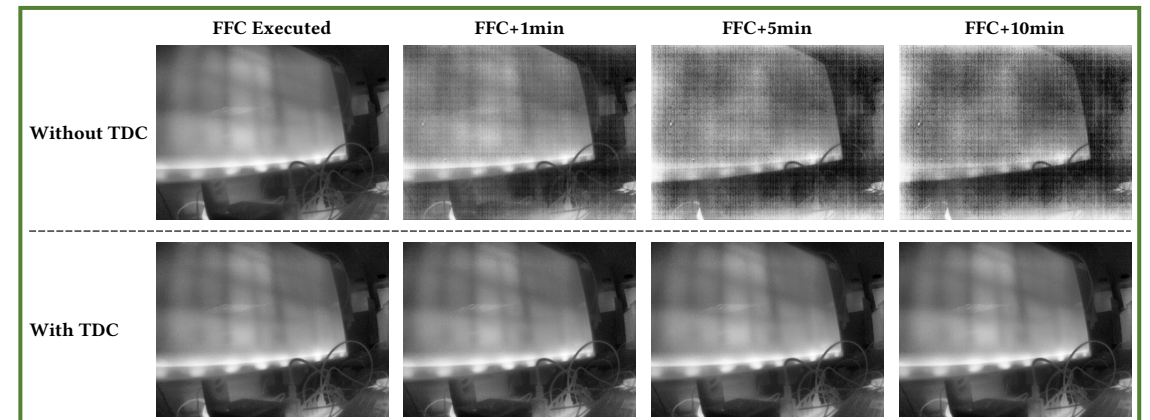
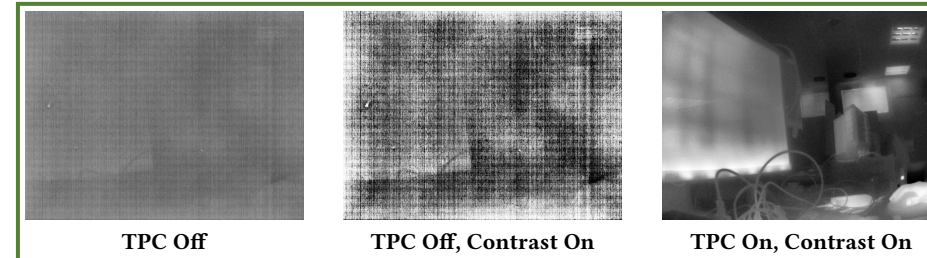
- Free from ghosting and blurring
 - Fixed-pattern noise removed

- **Thermal Drift Compensation (TDC)**

- Without TDC: the thermal drift caused the image degradation starting after 1 minute
 - With TDC: The human-sighted image quality is maintained after 10 minutes

- **Contrast Enhancement**

- TPHE / TPHE + CLAHE

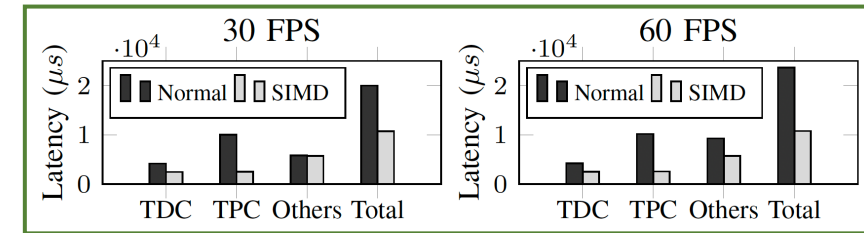


Specs

Evaluation – SW Optimizations

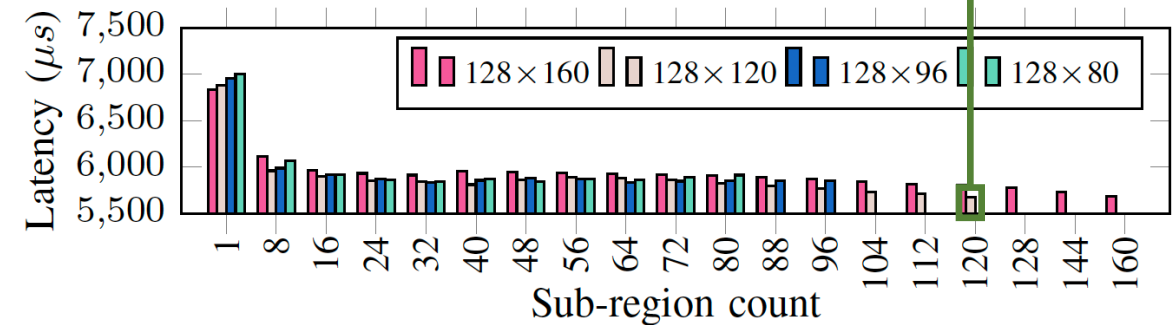
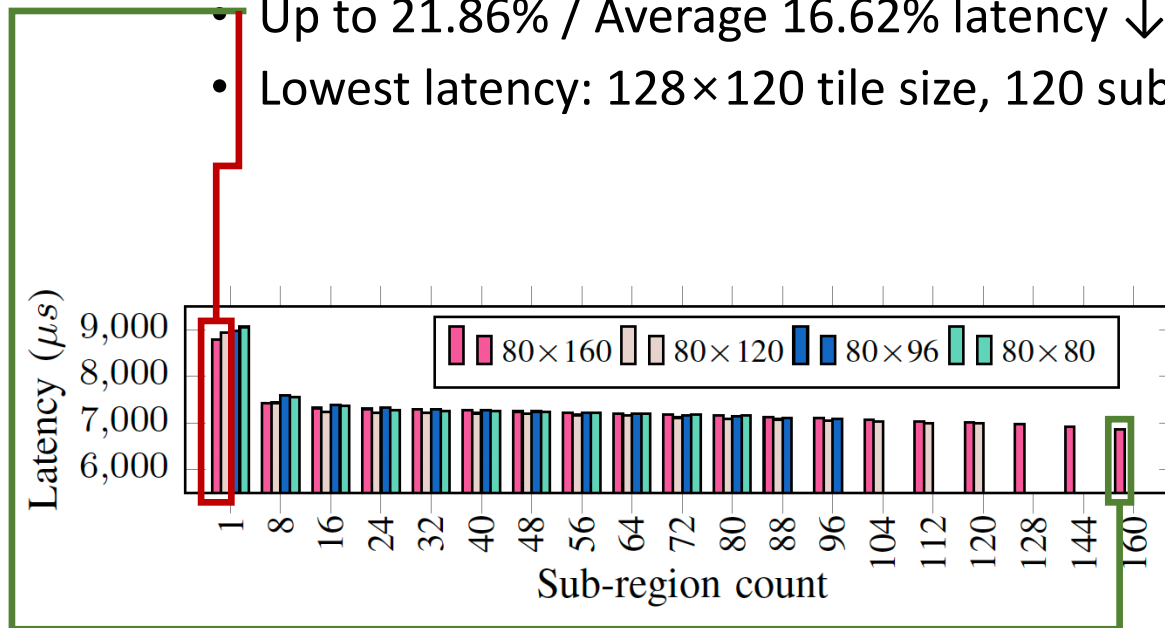
- **SIMD Kernel**

- 46.4% / 54.5% latency ↓ @ 30 / 60 FPS
→ 1.87× / 2.2× improved throughput



- **Regional Iteration**

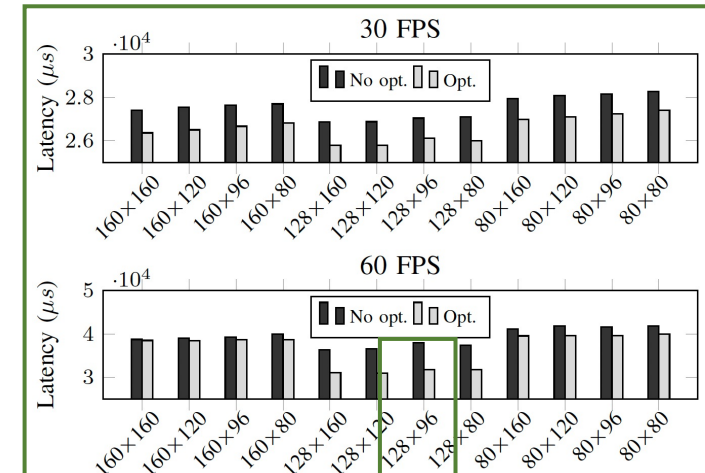
- Up to 21.86% / Average 16.62% latency ↓
- Lowest latency: 128×120 tile size, 120 sub-regions



Evaluation – SW Optimizations

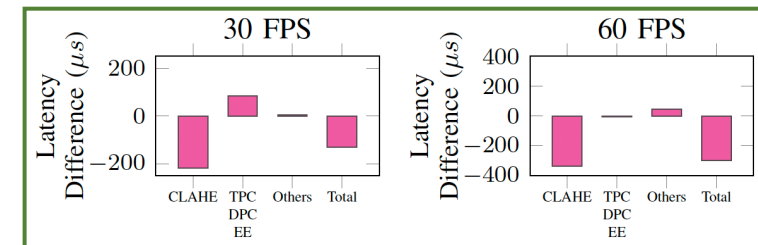
- **VLIW Optimization**

- Avg. 3.72% / 7.18% latency ↓ @ 30 / 60 FPS
- Up to 16.43% latency ↓ @ 60 FPS, 128×96



- **Static Cache Memory Partitioning**

- Avg. 0.54% / 1% latency ↓ (131 μs, 299 μs)
- Up to 4.27% latency ↓ @ 60 FPS, 128×120 (1265 μs)



Evaluation – Comparative Analysis

- **vs. SOTA**

- Maximum power under 2.2 W
- 9.42% / 9.96% power efficiency ↑ @ 30 / 60 FPS
- 2.8% power efficiency ↓ with CLAHE

Works	Syst. Compon.	Resolut.	FPS	NUC Stack	Contrast Enhanc.	Power (W)	Power Effic. (FPS / W)
This work	SoC + IRFPA	640×480	30	TPC+TDC+FFC+DPC	HE-variant+CLAHE HE-variant	1.837 ^a / 1.865 ^b 1.656	16.33 ^a / 16.09 ^b 18.12
			60	TPC+TDC+FFC+DPC	HE-variant+CLAHE HE-variant	2.145 ^a / 2.160 ^b 1.908	27.97 ^a / 27.78 ^b 31.45
[23]	FPGA + IRFPA	640×480	30 / 111	TPC+FFC+DPC	HE	1.812* / 6.970*	16.56* / 15.96*
[24]	FPGA + IRFPA	640×480	60 / 142	TPC+TDC+FFC+DPC	Min-max stretching	2.098*(60 FPS)	28.60*(60 FPS)
[43]	MCU + Camera	160×120	8.7	Camera dependent	HE-variant	0.920	9.46

^aEVE CLAHE mode / ^bDSP CLAHE mode. *FPGA on-chip power, other system devices are not measured.

- **Potential for Further Improvement**

- Peak core load 57.5% (DSP 0)
- Lower EVE utilization → Room for further distribution

Core	30 FPS (%)			60 FPS (%)		
	HE ^a	DC ^b	EC ^c	HE ^a	DC ^b	EC ^c
Coretx-M4 0	6.90	14.20	12.30	9.80	21.20	21.00
Coretx-M4 1	1.10	5.60	1.20	1.20	11.80	1.60
DSP 0	23.80	26.40	12.20	26.30	46.70	57.50
DSP 1	8.60	26.20	12.80	17.70	55.70	30.80
EVE	0.70	0.70	6.30	0.70	0.90	12.00

^aHE-only mode / ^bDSP CLAHE mode / ^cEVE CLAHE mode.

Conclusion

- The proposed **heterogeneous SoC**-based imaging system provides compact yet high-performance thermal imaging, enabling the **exclusion of the FPGA** chip, which was previously essential for **CLAHE**.
- Our system seamlessly processes the **14-bit, 640×480 (VGA)** resolution, **60 FPS** IR video with the thermal-drift-aware **three-layer NUC** (TDC, TPC, DPC) and **two-layer contrast enhancements** (TPHE, CLAHE).
- Our design consumed a maximum of 2160 mW of power at DSP CLAHE mode, showing its feasibility in resource-constrained systems.
- The maximum DSP core load of 57.5% and room for workload distribution (low EVE load) allow for adaptation to higher throughput videos (1280×1024) with further optimization.

Thank You!

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